

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in this application:

LISTING OF CLAIMS:

Claims 1 to 8. (Canceled).

9. (Currently Amended) A sensor system, comprising:

a thin-film sensor including a first surface, the first surface having at least two contact areas;

a printed circuit board including a second surface, the second surface having at least two contact pads, the thin-film sensor arranged relative to the second surface of the printed circuit board such that the first surface of the thin-film sensor having the at least two contact areas faces away from the second surface of the printed circuit board having the at least two contact pads;

a conductive adhesive adapted to transmit sensor currents from the thin-film sensor to the printed circuit board, the conductive adhesive adhering to the contact areas of the thin-film sensor and the contact pads on the second surface of the printed circuit board, each contact area joined by the conductive adhesive to a corresponding contact pad of the printed circuit board; and

a mounting adhesive applied on the second surface of the printed circuit board in between the contact pads and arranged at least in one partial area between the thin-film sensor and the second surface of the printed circuit board.

10. (Previously Presented) The sensor system according to claim 9, wherein the thin-film sensor is arranged as one of (a) a humidity sensor and (b) a moisture sensor.

11. (Previously Presented) The sensor system according to claim 9, wherein the thin-film sensor is adapted to operate on a capacitive measuring principle.

Claims 12 and 13. (Canceled).

14. (Previously Presented) The sensor system according to claim 9, wherein a thermal conductivity of the mounting adhesive is greater than 0.3 W/(m·K).

15. (Currently Amended) A method for manufacturing a sensor system, comprising:

applying a mounting adhesive on one of (a) a surface of a printed circuit board and (b) a surface of a thin-film sensor;

placing the thin-film sensor relative to the surface of the printed circuit board such that a surface of the thin-film sensor on which contact areas ~~is~~ are arranged is facing away from the surface of the printed circuit board and such that the mounting adhesive is arranged between at least two contact pads arranged on the surface of the printed circuit board and at least in one partial area between the thin-film sensor and the surface of the printed circuit board; and

bonding the thin-film sensor to the printed circuit board such that the contact areas of the thin-film sensor are electrically connected by a conductive adhesive to the contact pads on the surface of the printed circuit board.

16. (Previously Presented) The method according to claim 15, wherein the mounting adhesive is applied in the applying step prior to the placing step.

17. (Currently Amended) A sensor system, comprising:

thin-film sensing means including a first surface, the first surface having at least two contact areas;

printed circuit board means including a second surface, the second surface having at least two contact pads, the thin-film sensing means arranged relative to the second surface of the printed circuit board means such that the first surface of the thin-film sensing means having the at least two contact areas faces away from the second surface of the printed circuit board means having the at least two contact pads;

conductive adhering means for transmitting sensor currents from the thin-film sensing means to the printed circuit board means, the conductive adhering means adhering to the contact areas of the thin-film sensing means and the contact pads on the second surface of the printed circuit board means, each contact area joined by

the conductive adhering means to a corresponding contact pad of the printed circuit board means; and

mounting adhering means applied on the second surface of the printed circuit board means in between the contact pads and arranged at least in one partial area between the thin-film sensing means and the second surface of the printed circuit board means.

18. (Currently Amended) The sensor system according to claim 9, wherein the first surface of the thin-film sensor includes exactly two contact areas, and the second surface of the printed circuit board includes exactly two contact pads.

19. (Previously Presented) The method according to claim 15, wherein the surface of the thin-film sensor includes exactly two contact areas, and the surface of the printed circuit board includes exactly two contact pads.

20. (Currently Amended) The sensor system according to claim 17, wherein the first surface of the thin-film sensing means includes exactly two contact areas, and the second surface of the printed circuit board means includes exactly two contact pads.